

SPECIFICATIONS

Current Rating : 3 Amp Max

Insulator resistance :

5000 M ohms Min at 1000V DC

Dielectric withstand Voltage :

1000V AC R.M.S for 1 Mintue

Operating Temperature : -55°C~ +105°C

MATERIAL :

Housing :P.B.T (UL 94V-0), Black

Terminal : t=0.40mm Copper Alloy, Gold Plating


ORDER INFORMATION:

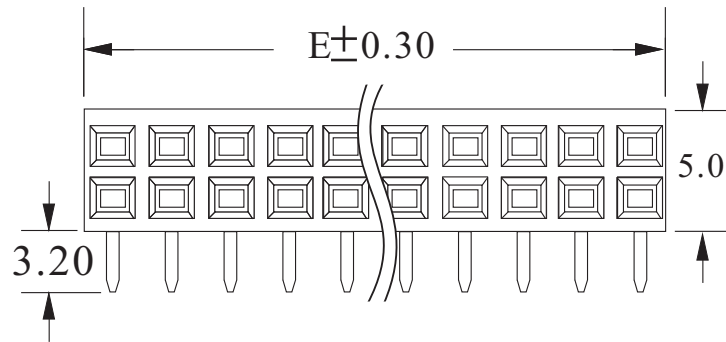
HFDR1 - XX 4 - X0 - X - XX - X
 a b c d e f g

- a. Pin of numbers: 04 ~ 80 b. Pastic Thick : 4: 8.5mm
- c. Plated selection:
 0 : Tin plated
 1 : Gold flash
 2 : 5u" Gold on Contact Area
 3 : 15u" Gold on Contact Area
 4 : 30u" Gold on Contact Area
 5 : Duplex Gold Flash on Contact Area
 6 : Duplex 5u" Gold on Contact Area
 7 : Duplex 15u" Gold on Contact Area
 8 : Duplex 30u" Gold on Contact Area
- d. Solder Pin length :
 1 : A=3.2mm
- e. Plastic Color :
 B : black color
- f. Plastic material selection:
 P : P.B.T (off料)
 E : P.B.T (新料)
- g. Pack selection:
 D : Disk Pack

VERSION & EC DESCRIPTION

DATE	VERSION	PAGE	DESCRIPTION
2004/03/30	A	20-21	Add HFDR1-XX4 Plan
2004/10/15	A	20	Revise Specifications
2005/03/09	A	20-21	Add Pack : Disk

GENAL TOLERANCE .X ± 0.3 .XX ± 0.25	DRAW DATE	2004/03/30 H. D. LI	PART NO	HFDR1-XX4-X0-X-XX-X
	DESIGN	H. D. LI	TITLE	2.54 2xXX 母座 H=8.5 90度 DIP 黑 PBT
	CHECKED	Y. M. LU	 宏揚精密有限公司 HOJAR PRECISION CO., LTD.	
UNIT :mm	APPROVED	J. F. KANG		

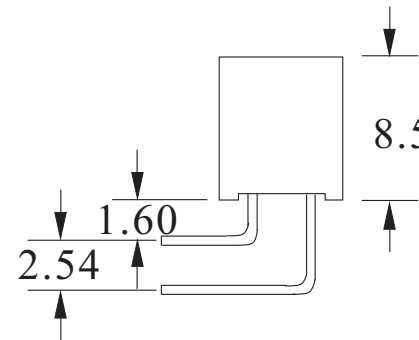
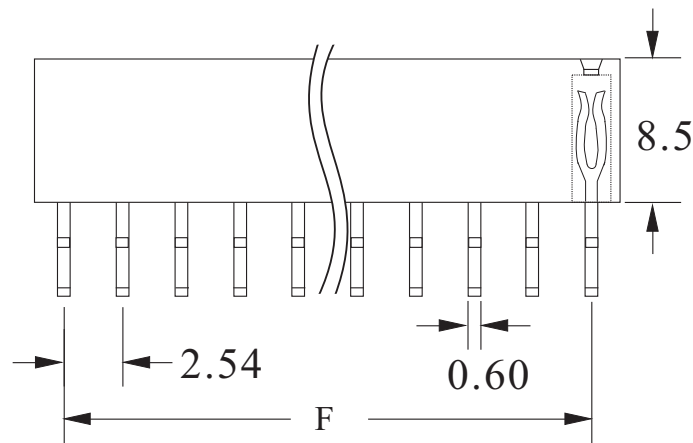


$$E = (\text{No of Posotion Per Row}) \times 2.54 + 0.5$$

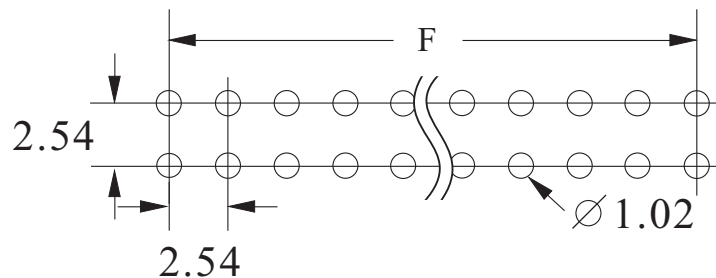
$$[(\text{No of Posotion Per Row}) \times 0.100] + 0.020$$


$$F = (\text{No of Posotion Per Row} - 1) \times 2.54$$

$$[(\text{No of Posotion Per Row} - 1) \times 0.100]$$



Recommended P.C.Board Hole Layout :



GENAL TOLERANCE .X ± 0.3 .XX ± 0.25	DRAW 2004/03/30 DATE H. D. LI	PART NO HFDR1-XX4-X0-X-XX-X
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